

## Maximum Ratings, NPN Transistor Element (Q1) (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V <sub>CBO</sub>	60	V
Collector-Emitter Voltage	V <sub>CEO</sub>	40	V
Emitter-Base Voltage	V <sub>EBO</sub>	6.0	V
Collector Current - Continuous (Note 5)	I <sub>C</sub>	600	mA

## Maximum Ratings, Zener Element (Z1) (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Forward Voltage @ I <sub>F</sub> = 10mA	V <sub>F</sub>	0.9	V

## Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P <sub>D</sub>	300	mW
Thermal Resistance, Junction to Ambient (Note 5)	R <sub>θJA</sub>	417	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

Note: 5. Part mounted on FR-4 board with recommended pad layout, which can be found on our website at <http://www.diodes.com/package-outlines.html>.

## Electrical Characteristics, NPN Transistor Element (Q1) (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Max	Unit	Test Condition
<b>OFF CHARACTERISTICS (Note 6)</b>					
Collector-Base Breakdown Voltage	V <sub>(BR)CBO</sub>	60	—	V	I <sub>C</sub> = 100μA, I <sub>E</sub> = 0
Collector-Emitter Breakdown Voltage	V <sub>(BR)CEO</sub>	40	—	V	I <sub>C</sub> = 1.0mA, I <sub>B</sub> = 0
Emitter-Base Breakdown Voltage	V <sub>(BR)EBO</sub>	6	—	V	I <sub>E</sub> = 100μA, I <sub>C</sub> = 0
Collector Cutoff Current	I <sub>CEX</sub>	—	100	nA	V <sub>CE</sub> = 35V, V <sub>EB(OFF)</sub> = 0.4V
Base Cutoff Current	I <sub>BL</sub>	—	100	nA	V <sub>CE</sub> = 35V, V <sub>EB(OFF)</sub> = 0.4V
<b>ON CHARACTERISTICS (Note 6)</b>					
DC Current Gain	h <sub>FE</sub>	20	—	—	I <sub>C</sub> = 100μA, V <sub>CE</sub> = 1.0V
		40	—		I <sub>C</sub> = 1.0mA, V <sub>CE</sub> = 1.0V
		80	—		I <sub>C</sub> = 10mA, V <sub>CE</sub> = 1.0V
		100	300		I <sub>C</sub> = 150mA, V <sub>CE</sub> = 1.0V
		40	—		I <sub>C</sub> = 500mA, V <sub>CE</sub> = 2.0V
Collector-Emitter Saturation Voltage	V <sub>CE(SAT)</sub>	—	0.40 0.75	V	I <sub>C</sub> = 150mA, I <sub>B</sub> = 15mA I <sub>C</sub> = 500mA, I <sub>B</sub> = 50mA
Base-Emitter Saturation Voltage	V <sub>BE(SAT)</sub>	0.75 —	0.95 1.2	V	I <sub>C</sub> = 150mA, I <sub>B</sub> = 15mA I <sub>C</sub> = 500mA, I <sub>B</sub> = 50mA

## Electrical Characteristics, Zener Element (Z1) (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Zener Voltage Range (Note 6)				Maximum Zener Impedance		Maximum Reverse Leakage Current (Note 6)	
V <sub>Z</sub> @ I <sub>ZT</sub>			I <sub>ZT</sub>	Z <sub>zt</sub> @ I <sub>ZT</sub>	Z <sub>zk</sub> @ I <sub>zk</sub> = 0.5mA	I <sub>R</sub>	@ V <sub>R</sub>
Nom (V)	Min (V)	Max (V)	mA		Ω	μA	V
5.6	5.49	5.73	5	60	200	1.0	2.5

Note: 6. Short duration pulse test used to minimize self-heating effect.

# NPN Transistor (Q1)

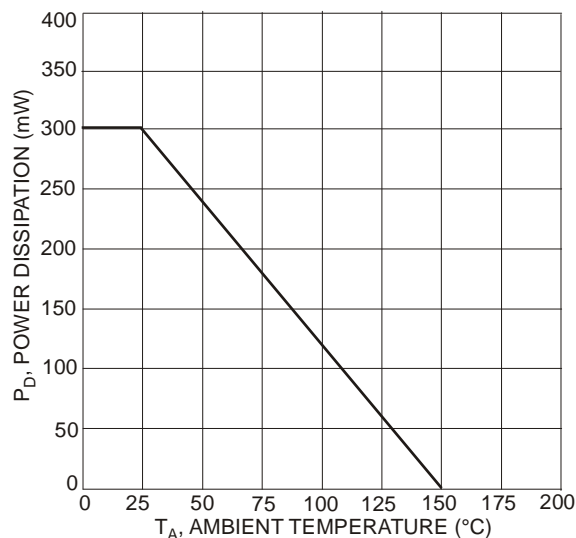


Fig. 1 Power Dissipation vs. Ambient Temperature (Total Device)

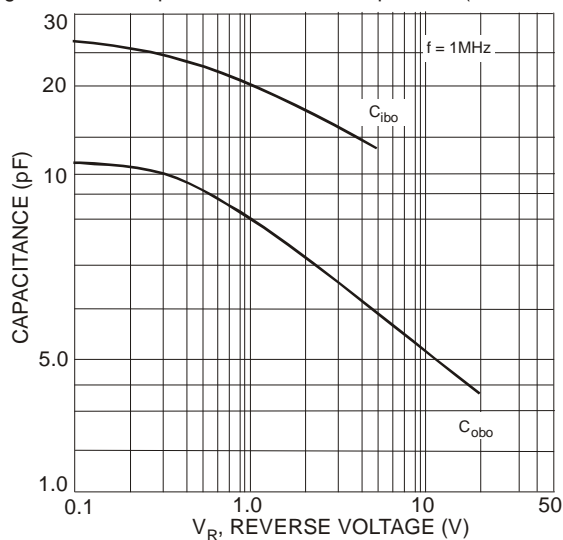


Fig. 3 Typical Capacitance Characteristics

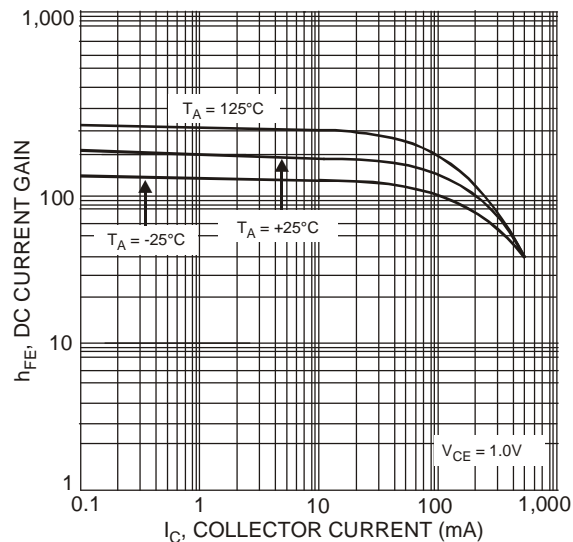


Fig. 2 Typical DC Current Gain vs. Collector Current

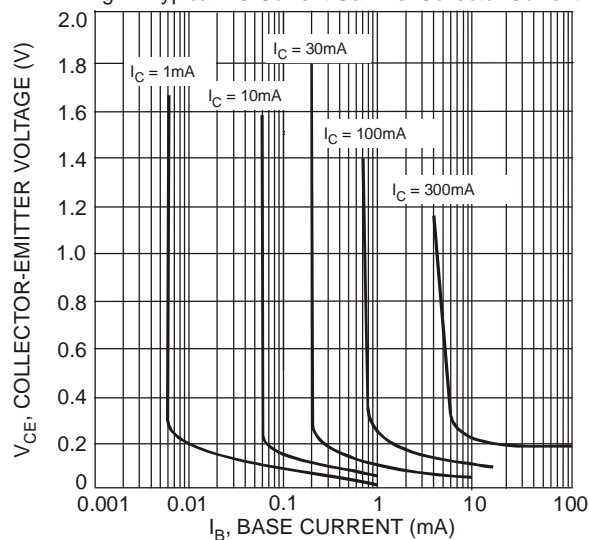


Fig. 4 Typical Collector Saturation Region

**NPN Transistor (Q1)** (Continued)

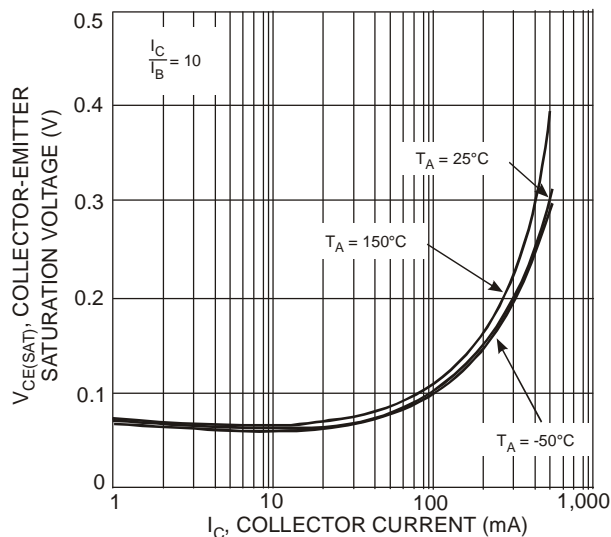


Fig. 5 Typical Collector-Emitter Saturation Voltage vs. Collector Current

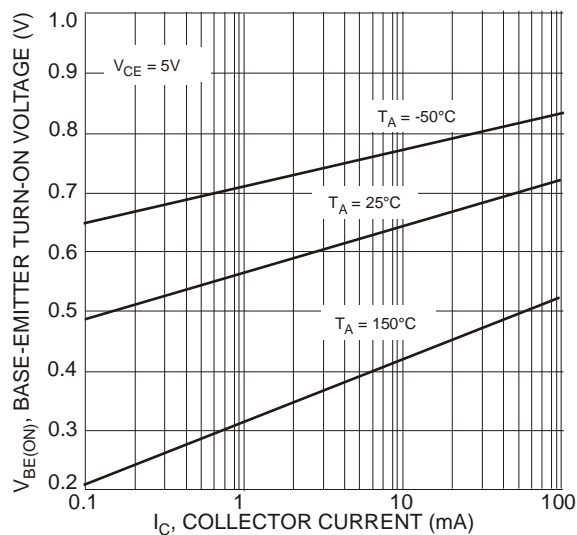


Fig. 6 Typical Base-Emitter Turn-On Voltage vs. Collector Current

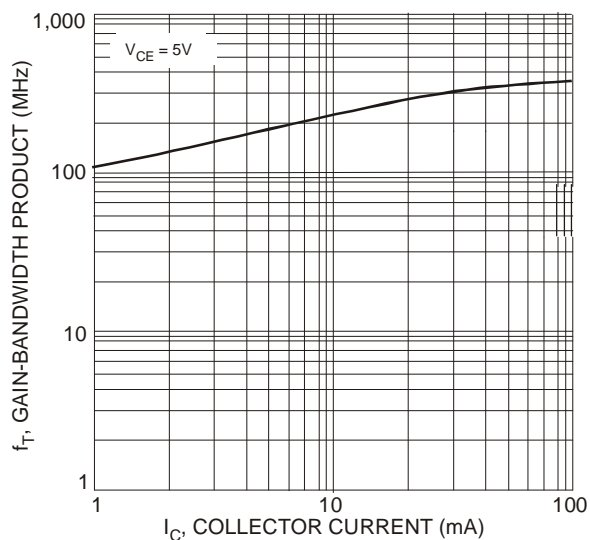


Fig. 7 Typical Gain-Bandwidth Product vs. Collector Current

## Zener (Z1)

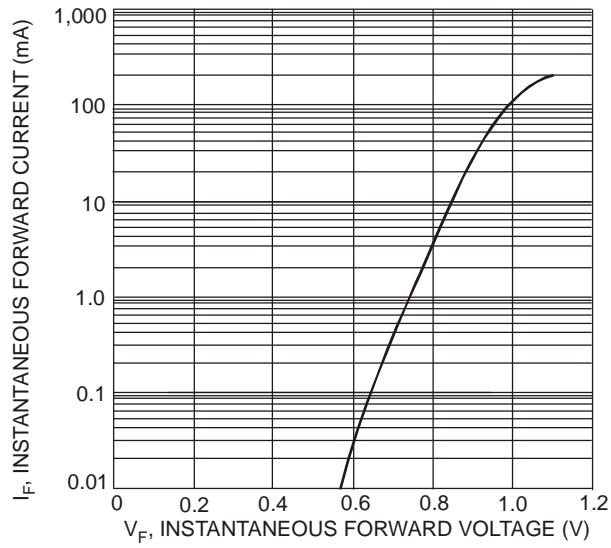
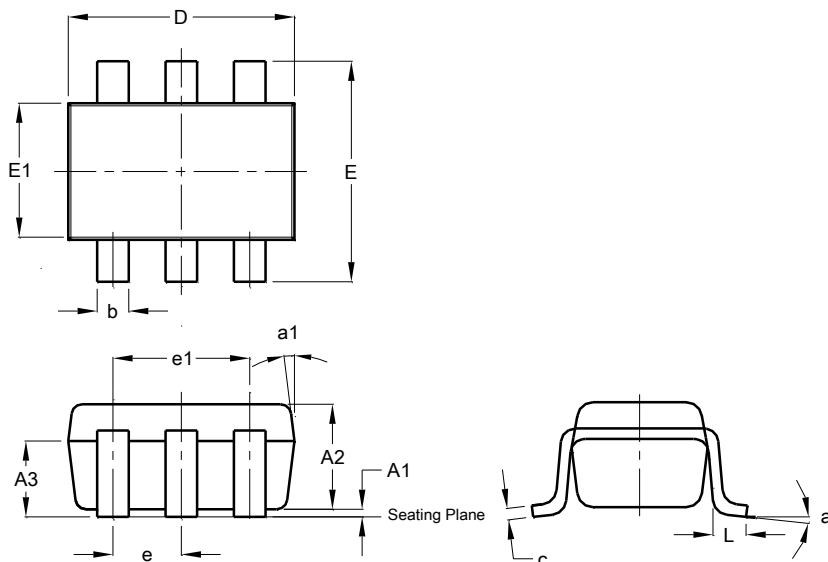


Fig. 8 Typical Forward Characteristics

## Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOT26 (SC74R)

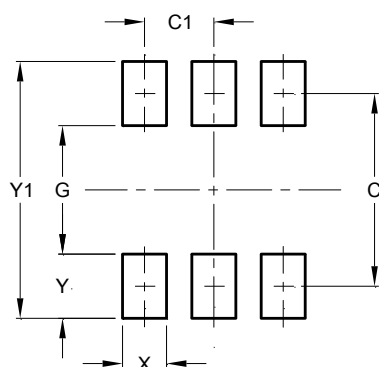


SOT26 (SC74R)			
Dim	Min	Max	Typ
A1	0.013	0.10	0.05
A2	1.00	1.30	1.10
A3	0.70	0.80	0.75
b	0.35	0.50	0.38
c	0.10	0.20	0.15
D	2.90	3.10	3.00
e	-	-	0.95
e1	-	-	1.90
E	2.70	3.00	2.80
E1	1.50	1.70	1.60
L	0.35	0.55	0.40
a	-	-	8°
a1	-	-	7°
All Dimensions in mm			

## Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOT26 (SC74R)



Dimensions	Value (in mm)
C	2.40
C1	0.95
G	1.60
X	0.55
Y	0.80
Y1	3.20

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